

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

5     **Listing of Claims**

Claims 1 - 29 (canceled)

Claim 30 (new):           A modular sprayjet cooling system for cooling one or more components on a board by spraying the one or more components with a cooling fluid  
10     during operation of the one or more components, comprising:

          an enclosure defining an internal chamber, the chamber being configured to contain the board, wherein the chamber can be readily opened and closed by hand for external access to the chamber;

          an electrical connector located within the chamber, the electrical connector being  
15     configured to electrically connect to the board to enable the operation of the one or more components;

          a sprayer located within the chamber, the sprayer being configured to spray the one or more components with the cooling fluid; and

          a fluid connection port configured to provide fluid communication between the  
20     enclosure and an external condenser;

          wherein when the chamber is opened, the board can be readily removed and replaced by hand; and

          wherein when the chamber is closed, the chamber is sealed such that cooling fluid  
25     cannot leak out of the chamber.

Claim 31 (new):           The modular sprayjet cooling system of claim 30, and further comprising a condenser in fluid communication with the enclosure via the fluid connection port.

Claim 32 (new):           The modular sprayjet cooling system of claim 30, and further comprising:

          a second sprayer located within the chamber, the second sprayer being configured to spray the one or more components with the cooling fluid; and

5           an adjustment mechanism configured to support the second sprayer at a distance from the board that is adjustable relative to the distance between the first sprayer and the board.

Claim 33 (new):           The modular sprayjet cooling system of claim 32, wherein the  
10          adjustment mechanism includes a bracket that connects the second sprayer to the enclosure.

Claim 34 (new):           The modular sprayjet cooling system of claim 32, wherein the  
15          adjustment mechanism includes a bracket that connects the second sprayer to the board.

Claim 35 (new):           The modular sprayjet cooling system of claim 30, wherein the  
          sprayer is an incremental sprayer.

Claim 36 (new):           The modular sprayjet cooling system of claim 35, wherein the  
20          sprayer is a thermal inkjet-type sprayer.

Claim 37 (new):           An electronic device comprising a modular sprayjet cooling  
          system as recited in claim 30.

25          Claim 38 (new):           The electronic device of claim 37, and further comprising a second modular sprayjet cooling system as recited in claim 30.

Claim 39 (new): A modular sprayjet cooling system for cooling one or more components on a board by spraying the one or more components with a cooling fluid during operation of the one or more components, comprising:

5 a means for enclosing the board, wherein the means for enclosing can be readily opened and closed by hand for external access to the enclosed board so as to allow the board to be readily removed and replaced by hand;

a means for electrically connecting the enclosed board to enable the operation of the one or more components;

a means for spraying the one or more components with the cooling fluid; and

10 a means for allowing sprayed cooling fluid to be passed between the means for enclosing and an external cooling unit;

wherein when the means for enclosing is closed, it is sealed such that cooling fluid cannot leak out of the means for enclosing.

15 Claim 40 (new): A method for cooling one or more components on a board by spraying the one or more components with a cooling fluid during operation of the one or more components, comprising:

20 enclosing the board in an enclosure, wherein the enclosure can be readily opened and closed by hand for external access to the enclosed board so as to allow the board to be readily removed and replaced by hand, and wherein when the enclosure is closed, it is sealed such that cooling fluid cannot leak out of the enclosure;

electrically connecting the enclosed board to enable the operation of the one or more components;

spraying the one or more components with the cooling fluid; and

25 circulating the sprayed cooling fluid through an external condenser via a fluid connection port configured to provide fluid communication between the enclosure and an external condenser.

Claim 41 (new): A method for electrically connecting a board having one or more components to an electrical connector of an electronic device, and for providing the board with a cooling fluid for cooling the one or more components via a device fluid connection port, comprising:

5 inserting the board into an enclosure defining an internal chamber, the enclosure including a first electrical connector configured to electrically connect to the inserted board, a second electrical connector in electrical communication with the first electrical connector, a sprayer configured to spray the one or more components on the inserted board with the cooling fluid, and an enclosure fluid connection port;

10 sealing the chamber such that cooling fluid cannot leak out of the chamber; and  
inserting the enclosure into a bay in the electronic device, wherein the second electrical connector is configured to mate with the electrical connector of the electronic device when the enclosure is inserted into the bay, and wherein the enclosure fluid connection port is configured to mate with the device fluid connection port when the  
15 enclosure is inserted into the bay.

Claim 42 (new): A method for cooling one or more components on a board, comprising:

20 adjusting the spray height of a first sprayer configured to spray cooling fluid on the one or more components with respect to the spray height of a second sprayer configured to spray the one or more components with the cooling fluid; and

spraying the one or more components with cooling fluid from the first and second sprayers during operation of the one or more components.

25 Claim 43 (new): An apparatus for cooling one or more components on a board, comprising:

a first means for spraying the one or more components with cooling fluid during operation of the one or more components;

30 a first means for spraying the one or more components with cooling fluid during operation of the one or more components; and

a means for adjusting the spray height of the first means for spraying with respect to the spray height of the second means for spraying.